

**P-2.5 COMMITTEE FOR TANTALUM & NIOBIUM CAPACITORS
MINUTES: WEDNESDAY, April 18, 2007, San Diego, CA**

1.1 Membership and attendance

ATTENDEES:

**Mike Lauri – IBM
Carl Lindquist – SOC America, Inc
Jayson Young – Kemet
Dave Toomey – Vishay
Mihee Lee – Samsung
Laird Macomber – Cornell Dubilier
Mike Griffith – KOA
Jack Culloton - Vishay Intertechnology, Inc.
Dave Richardson - Vishay**

1.2 Agenda approved

1.3 Approve minutes of last meeting , Reno, NV, Sept 27. 2006

Minutes approved. Suggest a roster to ensure that all members are included on correspondence.

1.4 Correspondence -None

2. OLD BUSINESS

2.1 Reports -None

**2.1.1 Passive Component Steering Committee (S.1).....Mike Lauri
Future meeting dates and locations-San Antonio - Sept 24-27**

**2.1.2 Government Specifications and Standards..... DSCC Representative –
No Report**

2.2 Surface Mount Tantalum Capacitors

2.2.1 Status: Standard (EIA-535BAAC), Low ESR (EIA-535BAAE)

Discussion of new case sizes, ratings, or products....All Members

Limited focus to a single project EIA 809 is underway so no new updates on 535.

Suggest was made to meet in Maine (targeting July 30th to Aug 1st). Group agreed to meet at this time.

Lead-frame less/face down termination molded specification?

The group will not do a signal spec for facedown. Will instead include this in the current 535 spec. Will note facedown, TAC, and standard termination as three configurations included in spec. Goal of July 30th meeting will be to complete 809 and create outline for 535.

2.3 Hazardous Material IPC-1752 Spec EIA has JIG 101 that is out for first revision. Ed noted that the tool is widely used.

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2.4.1 Lead free solder topics - Tin Whiskers.....NO further report

2.5 Update EIA 809 Tantalum Applications Guide

Was reviewed in the working group on Apr 16th. Action items have been assigned to each member.

2.6.1 Review existing specifications: J-Std-020C, IPC-9503 (MSL passives), IPC-9504 (Assembly Process Simulation for Non-IC Devices)
IPC team needs input from P2.5 noting any component types that cannot meet 20C profiles (wave or reflow). Dave will participate on the IPC calls and provide updates.

2.7 Review and update EIA list of "active working projects

2.8 Review Niobium/NbO draft specification/ PN number 5075

2.9 Update EIA IS 717 Qualification specification PN 5097

Jayson will send out draft to group for review. Once reviewed, make changes and send out for ballot.

3. NEW BUSINESS

3.1.1 Address AEC Q200 Rev C preconditioning project

Team to present EIA's recommended changes to AEC Q200 preconditioning in May. Mary and Dave to attend.

3.1.2 Transferring solder Alum chip capacitors to P 2.5 group

Motion to change the title of the P2.5 (New scope is Solid Electrolytic Capacitors Including Aluminum, Niobium, and Tantalum). Voted and accepted new scope. The committee will take ownership of EIA 956 (Alum Electrolytic Chip Capacitor with Polymer Cathode) and the qual spec (PN 4984: Alum Electrolytic Solid Chip Qualification Spec) from P2.2. Voted and accepted ownership of these standards.

3.1.3 Mechanical Outlines

Jayson to provide Mechanical outline drawings to P4 group (SMD only).

3.2 Inputs for "All-Chairs Meeting"

Dave will discuss the need for a roster during the meeting.

4. ADJOURNMENT